





4 CHANNEL LOW CAPACITANCE TVS DIODE ARRAY

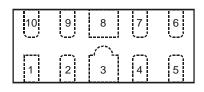
Features

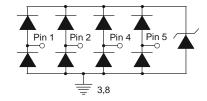
- IEC 61000-4-2 (ESD): Air ±15kV, Contact ±8kV
- 4 Channels of ESD Protection
- Low Channel Input Capacitance of 0.5pF Typical
- Typically Used at High Speed Ports such as USB 2.0, USB 3.0, IEEE1394, Serial ATA, DVI, HDMI, PCI
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: U-DFN2510-10
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiPdAu over Copper leadframe (Lead Free Plating).
 Solderable per MIL-STD-202, Method 208 ⁶⁴
- Weight: 0.039 grams (approximate)

Pin#	Description
1, 2, 4, 5	Input
6, 7, 9, 10	No Connection
3, 8	Ground





Pin Description (Top View)

Device Schematic

Ordering Information (Note 4)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
D5V0F4U10LP-7	Standard	TF2	7	8	3,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

TF2 YM

TF2 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: A = 2013)

M = Month (ex: 9 = September)

Date Code Key

Date Ct	lue itey	_			_							_	
Ye	ear	201	3	2014		2015	20	16	2017		2018		2019
Co	de	А		В		С)	Е		F		G
Moi	nth	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Co	de	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Current	I _{PP}	3.0	Α	8/20µs, Figure 3
ESD Protection – Contact Discharge	V _{ESD_Contact}	±8	kV	Standard IEC 61000-4-2
ESD Protection – Air Discharge	V_{ESD_Air}	±15	kV	Standard IEC 61000-4-2

Thermal Characteristics

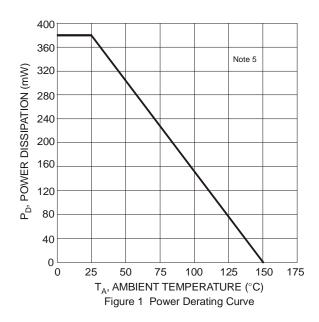
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	380	mW
Thermal Resistance, Junction to Ambient T _A = +25°C	$R_{ hetaJA}$	327	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

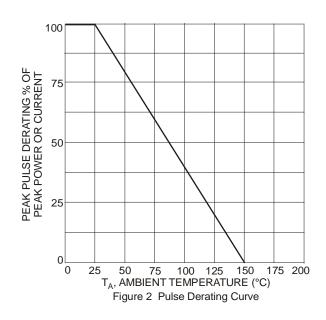
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Conditions
Reverse Working Voltage	V_{RWM}	_	_	5.5	V	_
Reverse Current (Note 6)	I _R	_	_	200	nA	V _R = 5.5V
Reverse Breakdown Voltage	V_{BR}	6.0	_	_	V	I _R = 1mA
Reverse Clamping Voltage, Positive Transients (Note 7)	V _{CL}	_	10	12	V	$I_{PP} = 1A, t_p = 8/20 \mu s$
Dynamic Resistance	R _{DYN}	_	1.0	_	Ω	$I_R = 1A$, $t_p = 8/20 \mu s$
Canacitanas (Nata 9)	0	_	0.4	0.65	pF	V _R = 2.5V, f = 1MHz
Capacitance (Note 8)	Ст	_	0.5	_	pF	$V_R = 0V$, $f = 1MHz$

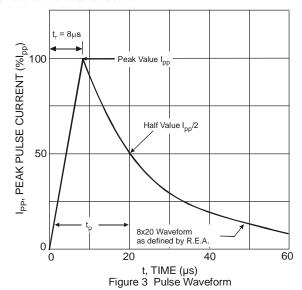
Notes:

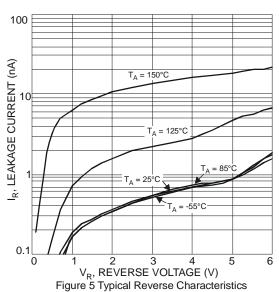
- 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com.
- 6. Short duration pulse test used to minimize self-heating effect.
- 7. Clamping voltage value is based on an 8x20µs peak pulse current (Ipp) waveform.
- 8. Measured from any I/O pin to GND.
- 9. For information on the impact of Diodes' USB 2.0 compatible ESD protectors on signal integrity including eye diagram plots, please refer to AN77 at the following URL: http://www.diodes.com/destools/appnote_dnote.html.

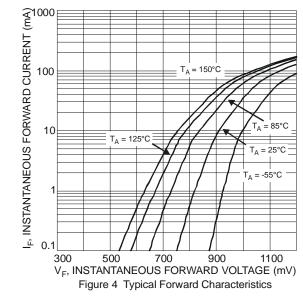












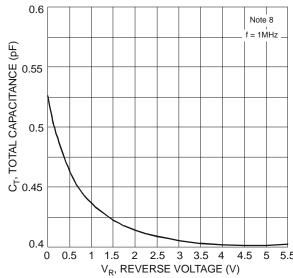
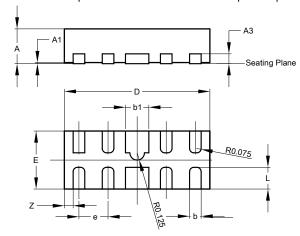


Figure 6 Total Capacitance vs. Reverse Voltage

Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

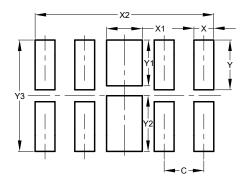


	U-DFN2510-10							
Dim	Min	Max	Тур					
Α	0.545	0.605	0.575					
A1	0	0.05	0.03					
A3	-	1	0.13					
b	0.15	0.25	0.20					
b1	035	0.45	0.40					
D	2.450	2.575	2.500					
е	-	-	0.50					
Е	0.950	1.075	1.000					
L	0.325	0.425	0.375					
Z	-	-	0.150					
AII D	All Dimensions in mm							



Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.500
X	0.250
X1	0.450
X2	2.250
Y	0.625
Y1	0.575
Y2	0.700
Y3	1.400

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